



Two component thermal conductive gel series

【Thermal Gap filler】

DATA SHEET



- Product picture -

FEATURES:

- $\geq 2.0W/m.K$ thermal conductivity
- Replacing traditional assembled sheet with phase-change material
- Dispensing can be done through various manual or automatic processes
- It is Soft, can eliminates assembly stress and damping
- After curing, the required thickness can be maintained

APPLICATIONS:

- Semiconductors and radiator
- LED lamps luminaries, automotive and consumer electronics
- Being dispensed or directly coated by all kinds of thickness and shape
- High performance CPU and display card processor

APPLICATION METHODS:

- Two component thermal conductive gel can be used in various ways, including automatic dispensing and manual coating.

The series of products are accord with standards of RoHS、HSF and HALOGEN.

STORAGE CONDITIONS:Storage in the darkness

STORAGE TEMPERATURE: $\leq 30^{\circ}C$

STORAGE HUMIDITY: $\leq 70\%$

SHELF LIFE: Six months storage conditions;
Unqualified for storage conditions: 3 months.

PACKING:

- According to different needs, it can be classified into to 400cc/20L and other capacity by the way of 1:1 perfusion packaging.

HTG-200D series of two-component thermal conductive gel is a kind of heat conductive paste which can be cured at room temperature. After curing, it presents a flexible rubber elastomer. It is suitable for the electronic/electrical field with heat dissipation demand. It is especially suitable for the occasion where different components share a large gap of radiator. It can be dispensed automatically to realize automatic operation.

BEFORE VULCANIZATION

Items		Parameter	Unit	Test Method
		HTG-200D		
Color	A component	white	-	Visual
	B component	gray	-	Visual
	After mixing	Gray white	-	Visual
State		High viscosity fluid	-	-
Density		≤ 2.5	g/cc	ASTM D 792
Mixing ratio		1:1	-	mass ratio
Curing condition	Surface curing	1(@25°C)	H	-
	Complete curing	24(@25°C)	H	-
	Accelerated curing	15(@100°C)	min	-

AFTER VULCANIZATION

Items	Parameter	Unit	Test Method
Thermal conductivity	≥ 2.0	W/m·K	ASTM D 5470
Thermal resistance	≤ 1.0 (@20psi&1mm)	$^{\circ}Cin^2/W$	ASTM D 5470
Hardness	35(± 5)	Shore C	ASTM D 2240
Breakdown voltage	≥ 10	KV/mm	ASTM D 149
Volume resistivity	$\geq 10^{12}$	$\Omega.cm$	ASTM D 254
Compression ratio	≥ 20 (@50Psi)	@	ASTM D 695
Tensile strength	≥ 0.1	Mpa	ASTM D 412
Elongation	≥ 100	%	ASTM D 412
Bonding strength	≥ 0.05	Mpa	ASTM D 624
spiral	≤ 1	%	ASTM G 120
Tear strength	≥ 0.6	KN/m	ASTM D 624
Permittivity	≥ 2	@1MHz	ASTM D 150
Dielectric loss	≤ 0.1	@1MHz	ASTM D 150
UL Certification	V-0	-	UL94
Operating Temperature	-40~150	$^{\circ}C$	IEC 60068-2-14

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